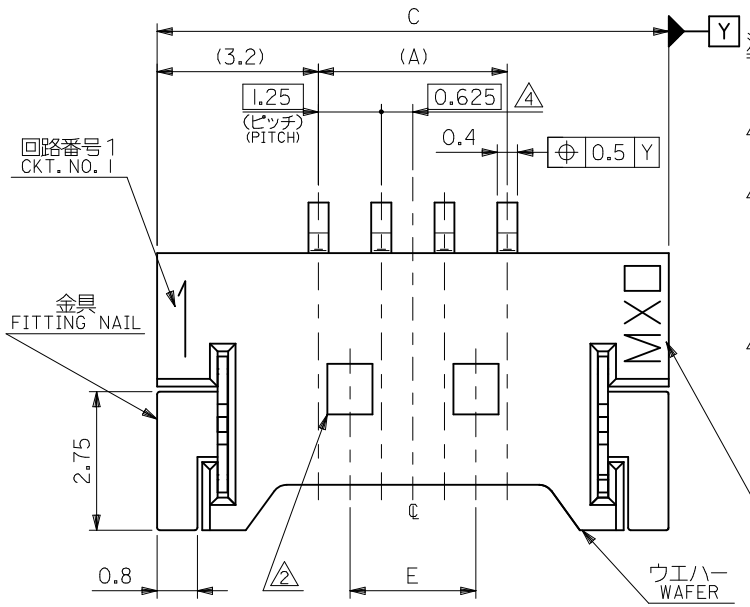


注記 NOTES

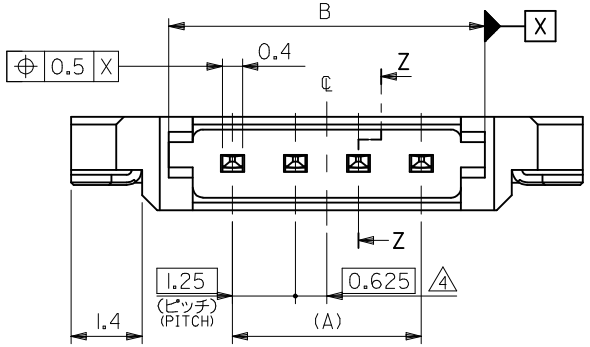
1. 嵌合相手： 51146 シリーズ
MATES WITH : 51146 SERIES

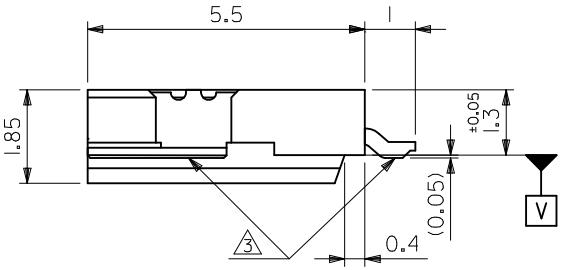
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.

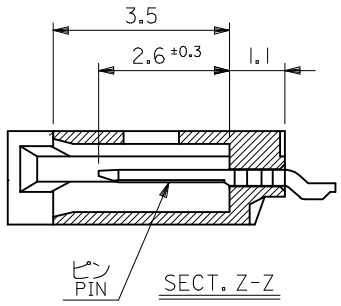
3. 基準面 V からのソルダーテールと金具の半田付け面のズレ量は、上方向に 0.05MAX. 下方向 0.15MAX. とし、相互のバラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM V
: UPPER DIRECTION 0.05MAX.
: LOWER DIRECTION 0.15MAX.
: OFFSET BETWEEN UPPER AND LOWER 0.1MAX.

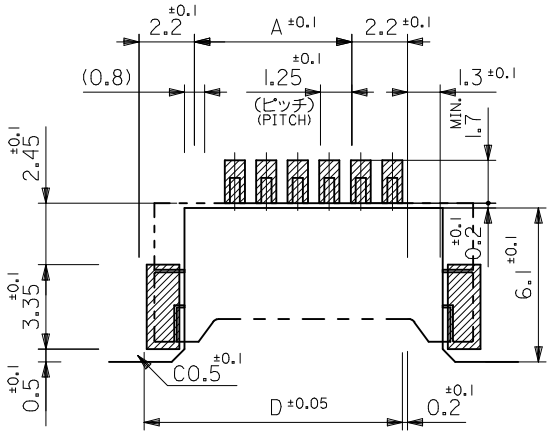
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.

5. 材質 MATERIAL
ウエハー WAFER : PPHS , UL94V-0
ピン : リン青銅（コンタクト部：金メッキ、テール部：半田メッキ）
PIN : PHOS-BRO (CONTACT : Au PLATING, TAIL : Sn-Pb PLATING)
金具 : リン青銅（半田メッキ）
FITTING NAIL : PHOS-BRO (Sn-Pb PLATING)









参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM. (REF.)

F	E	D	C	B	A	MATERIAL NO.	CKT. 極数
16.25	22.5	40.25	42.65	38.77	36.25	53779-3010	30
15	22.5	37.75	40.15	36.27	33.75	-2810	28
13.75	22.5	35.25	37.65	33.77	31.25	-2610	26
12.5	22.5	32.75	35.15	31.27	28.75	-2410	24
11.25	22.5	30.25	32.65	28.77	26.25	-2210	22
8.75	22.5	27.75	30.15	26.27	23.75	-2010	20
7.5	20	25.25	27.65	23.77	21.25	-1810	18
6.25	17.5	22.75	25.15	21.27	18.75	-1610	16
6.25	16.25	21.5	23.9	20.02	17.5	-1510	15
5	15	20.25	22.65	18.77	16.25	-1410	14
3.75	12.5	17.75	20.15	16.27	13.75	-1210	12
2.5	8.75	14	16.4	12.52	10	-0910	9
1.25	7.5	12.75	15.15	11.27	8.75	-0810	8
〃	5	10.25	12.65	8.77	6.25	-0610	6
〃	3.75	9	11.4	7.52	5	-0510	5
〃	2.5	7.75	10.15	6.27	3.75	-0410	4
〃	〃	6.5	8.9	5.02	2.5	-0310	3
〃	〃	5.25	7.65	3.77	1.25	53779-0210	2

MODEL NO. 53779-**10

REVISED
EC NO: J2008-4402 2008/07/01
DRWN:NAKAMURAA 2008/07/01
CH'KD:T. HARUYAMA 2008/11/18
APPR:NUKITA
DESCRIPTION
REV H

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

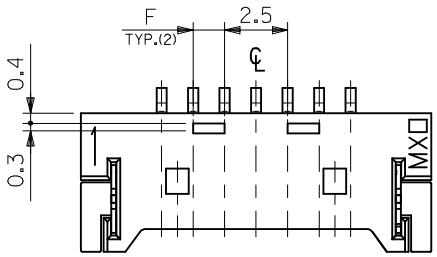
DRAWN BY: S.MATSUZAKI DATE: '01/05/11
CHECKED BY: T.YAMAGUCHI DATE: '01/05/11
APPROVED BY: T.YAMAGUCHI DATE: '01/05/11
MATERIAL NO.: SEE TABLE

TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASSY FOR SMT. (SHEET 1 OF 2)

MOLEX INCORPORATED

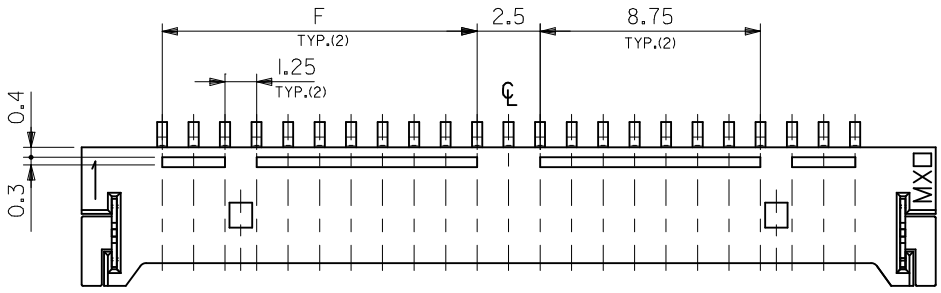
DOCUMENT NO.: SD-53779-003
SHEET NO.: 1 OF 2

SIZE A3



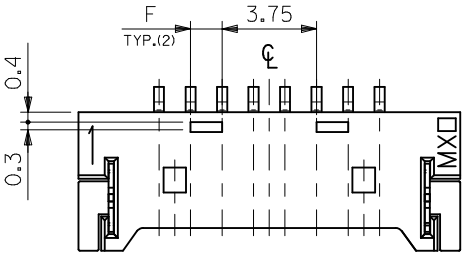
7～19極の奇数極に適用

APPLY FOR ODD CIRCUITS OF 7～19



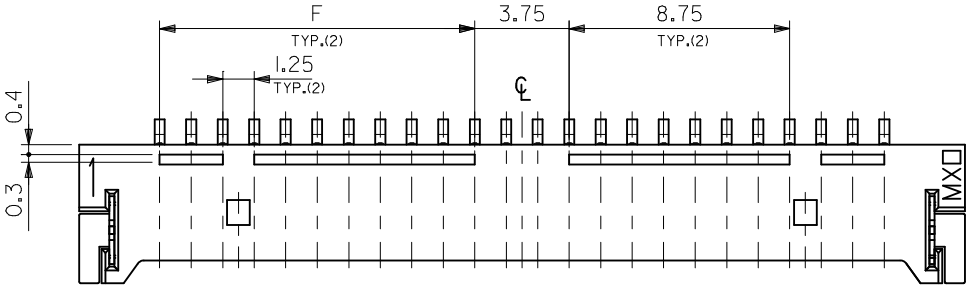
21極以上の奇数極に適用

APPLY FOR ODD CIRCUITS 21～29



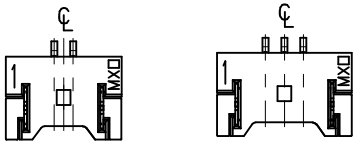
8～20極の偶数極に適用

APPLY FOR EVEN CIRCUITS OF 8～20



22極以上の偶数極に適用

APPLY FOR EVEN CIRCUITS 22～30



ロック形状図

LOCK CONFIGURATION

REVISED
EC NO: J2008-4402
DRWN:NAKAMURAA 2008/07/01
CH'KD:T. HARUYAMA 2008/07/01
APPR:NUKITA 2008/11/18
DESCRIPTION
REV
H

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: S.MAYSUZAKI DATE: '01/05/11
CHECKED BY: T.YAMAGUCHI DATE: '01/05/11
APPROVED BY: T.YAMAGUCHI DATE: '01/05/11

TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS FOR S.M.T. (SHEET 2 OF 2)

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-53779-003
SHEET NO.: 2 OF 2
SIZE: A3